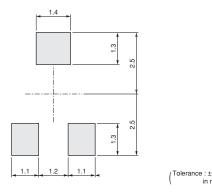
Mounting

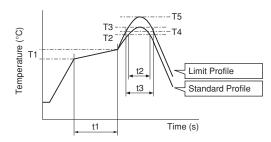
■ Land Pattern



■ Soldering Profile

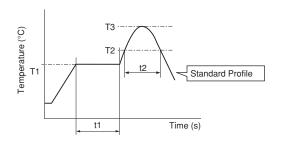
■ Reflow Soldering Profile

1. Soldering profile for lead free solder (96.5Sn/3.0Ag/0.5Cu)



Series	Standard Profile						Limit Profile					
	Pre-heating		Heating		Peak Temperature	Cycle	Pre-heating		Heating		Peak Temperature	Cycle
	Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)	of Reflow	Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)	(T5)	of Reflow
	°C	sec.	°C	sec.	°C	Time	°C	sec.	°C	sec.	°C	Time
PVG3	150 to 180	60 to 120	220	30 to 60	245±3	1	150 to 180	60 to 120	230	30 to 50	260 +5/-0	2

2. Soldering profile for Eutectic solder (63Sn/37Pb) (Limit profile: refer to 1)



Series Temperature	Cycle	
Temp. (T1) Time (t1) Temp. (T2) Time (t2) (T3) Of I	of Reflow	
°C sec. °C sec. °C	Time	
PVG3 150 60 to 120 183 30 230	1	

Soldering Iron

	Standard Condition							
Series	Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron				
	°C	sec.	w	Time				
PVG3	350±10	3 max.	30 max.	1				